

### Performance Specification

Model	I <sub>hold</sub> (A)	I <sub>trip</sub> (A)	V <sub>max interup</sub> (tV)	I <sub>max</sub> (A)	Pd <sub>max</sub> (W)	Maximum Time to Trip		Resistance(Ω)
						Current (A)	Time (S)	R <sub>min</sub> - R <sub>max</sub>
JK130-010	0.10	0.20	130	3	0.8	0.5	6	2.5-9.0
JK130-015	0.15	0.30	130	3	0.8	0.75	5.5	2.5-7.5
JK130-017	0.17	0.34	130	3	0.8	0.85	5.2	1.5-7.0
JK130-020	0.20	0.40	130	3	0.8	1.0	5.0	1.9-4.0
JK130-025	0.25	0.50	130	3	1.0	1.25	4.8	1.45-3.50
JK130-030	0.30	0.60	130	3	1.0	1.5	4.5	1.0-3.0
JK130-040	0.40	0.80	130	3	1.0	2.0	4.5	0.75-2.0
JK130-050	0.50	1.0	130	3	1.0	2.5	5.0	0.50-1.60
JK130-065	0.65	1.3	130	10	1.0	3.25	5.2	0.45-1.0
JK130-075	0.75	1.5	130	10	1.0	3.75	5.5	0.40-0.90
JK130-090	0.90	1.8	130	10	1.5	4.5	5.8	0.30-0.70
JK130-110	1.10	2.2	130	10	1.8	5.5	6.3	0.20-0.65
JK130-135	1.35	2.7	130	10	1.8	6.75	7.5	0.15-0.60
JK130-160	1.60	3.2	130	10	2.0	8.0	8	0.10-0.50
JK130-185	1.85	3.7	130	10	2.0	9.25	9	0.10-0.40
JK130-200	2.00	4.0	130	10	2.2	10.0	10	0.10-0.30
JK130-250	2.50	5.0	130	10	2.5	12.5	12	0.05-0.25

V<sub>max</sub> = Maximum operating voltage device can withstand without damage at rated current (I<sub>max</sub>).

I<sub>max</sub> = Maximum fault current device can withstand without damage at rated voltage (V<sub>max</sub>).

I<sub>hold</sub> = Hold Current. Maximum current device will not trip in 25°C still air.

I<sub>trip</sub> = Trip Current. Minimum current at which the device will always trip in 25°C still air.

Pd = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

R<sub>i min/max</sub> = Minimum/Maximum device resistance prior to tripping at 25°C.

R<sub>1max</sub> = Maximum device resistance is measured one hour post reflow.

CAUTION : Operation beyond the specified ratings may result in damage and possible arcing and flame.

## Physical Dimensions(mm.)

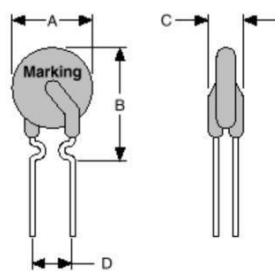


Fig.1

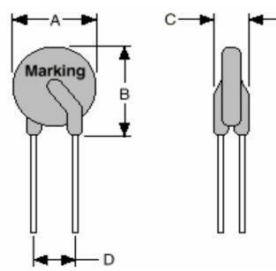


Fig.2

Model	Dimensions (mm)				Lead material Tinned matel(mm)	Shape Fig
	A(max)	B(max)	C(max)	D(typ)		
JK130-010	7.4	12.7	3.8	5.1	22AWG/Φ0.6	1
JK130-015	7.4	13.0	3.8	5.1	22AWG/Φ0.6	1
JK130-017	7.4	13.5	3.8	5.1	22AWG/Φ0.6	1
JK130-020	7.6	13.5	3.8	5.1	22AWG/Φ0.6	1
JK130-025	7.6	13.5	3.8	5.1	22AWG/Φ0.6	1
JK130-030	8.0	14.0	3.8	5.1	22AWG/Φ0.6	1
JK130-040	9.4	15.0	3.8	5.1	22AWG/Φ0.6	1
JK130-050	10.2	15.2	3.8	5.1	22AWG/Φ0.6	1
JK130-065	12.8	18.0	3.8	5.1	22AWG/Φ0.6	1
JK130-075	12.8	18.0	3.8	5.1	22AWG/Φ0.6	1
JK130-090	14.5	19.6	3.8	5.1	20AWG/Φ0.8	2
JK130-110	16.3	21.3	3.8	5.1	20AWG/Φ0.8	2
JK130-135	17.0	22.0	3.8	5.1	20AWG/Φ0.8	2
JK130-160	20	25	3.8	5.1	20AWG/Φ0.8	2
JK130-185	22	23	3.8	5.1	20AWG/Φ0.8	2
JK130-200	25	27	3.8	10.2	20AWG/Φ0.8	2
JK130-250	27	32	3.8	10.2	20AWG/Φ0.8	2

Note: ① Dimensions A, B, C is the maximum size, D values are typical tolerance of ± 0.75mm.

## Environmental Specifications

Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	±5% typical
Humidity aging	+85°C, 85% R.H. , 168 hours	±5% typical
Thermal shock	+85°C to -40°C, 20 times	±33% typical
Resistance to solvent	MIL-STD-202,Method 215	No change
Vibration	MIL-STD-202,Method 201	No change

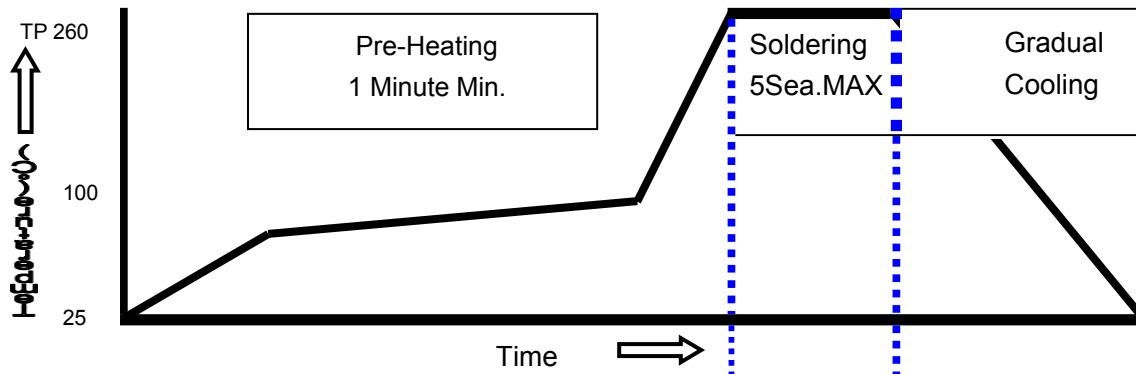
Ambient operating conditions : - 40 °C to +85 °C

Maximum surface temperature of the device in the tripped state is 125 °C

## Hold Versus Temperature

Model	Maximum ambient operating temperatures (°C)									
	-40°C	-20°C	0°C	25°C	30°C	40°C	50°C	60°C	70°C	85°C
JK130 series	147%	132%	118%	100%	90%	85%	76%	67%	60%	47%

## Soldering Parameters



### WAVE SOLDERING INFORMATION

Pre-Heating Zone	Max. ramping rate should not exceed 4°C/Sec.
Soldering Zone	Max. solder temperature should not exceed 260°C
Cooling Zone	Cooling by natural convection in air.

© Specifications are subject to change without notice.

## Packaging Quantity

JK130-010~JK130-065	1000Pcs/Bag
JK130-075~JK130-200	500 Pcs/Bag

Website: <http://www.jksemit.com>

For additional information, please contact your local Sales Representative.

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